

Virtual Special Issue on Physics and Modelling Issues in Low-Dimensional Device Design – Call For Paper

Nanometre-scaled devices has come to the edge of the technology, playing the pivotal role in realizing the next generation electronic systems and applications. This virtual special issue is the collection of the recent and emerging research works on low-dimensional device design collaborating with the [5th International Conference “2023 Devices for Integrated Circuit \(DevIC\)”](#). It comes the 5th event of the conference which will be held at Kalyani Government Engineering College from 7-8 April, 2023, organized by IEEE KGEC Student Branch Chapter in association with Department of ECE, KGEC and with technical partnership from IETE Kolkata Chapter and IEEE EDS Kolkata Chapter.

DevIC 2023 aims to bring together leading scientists, researchers, engineers, and scholar students to exchange and share their experiences, new ideas, and research results about all aspects of device technology and modelling to discuss the practical challenges encountered and the solutions adopted. The conference also will provide an opportunity to local, regional and international industries-service providers to present their technologies, products and services. Moreover, we want to continue our conference in the subsequent years also, to build a community against the conference. The aim and objective of DevIC 2023 is to provide a forum for the presentation and discussion of recent advances in solid-state devices, circuits and systems. The increasing level of integration for system-on-chip design made available by advances in silicon technology is more than ever before calling for a deeper interaction among technologists, device experts, IC designers, and system designers.

Topics of Interest

- Computational nanoelectronics and Photonics
- Quantum well, quantum wire, quantum dot, superlattice
- Modelling and Simulation of Nanoscale Device
- Design, Fabrication and Characterization of Novel Transistors
- Emerging Non-CMOS Devices
- Modelling of Quantum-Mechanical Devices
- Physics and Modelling of Submicron Microelectronic Devices
- High-frequency Device Simulation

Submission Instructions

- Special Issue Submission Deadline: May 15, 2023
- Conference paper submission should be made through the [conference website](#).
- Extended full papers could be submitted to the virtual special issue through [Editorial Manager](#).
- Invitation will be sent to the corresponding authors of the selected best papers of the conference.

Guest editors

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